



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR)**  
Stack Height: **6.5 mm [ .256 in ]**  
Module Orientation: **Right Angle**  
PCB Mounting Style: **Surface Mount**  
Connector System: **Cable-to-Board**

[All DDR2 SO DIMM SOCKETS \(30\)](#)

Features

Product Type Features

DRAM Type	Double Data Rate (DDR)
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Bays	2
Center Key	None
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	200
Number of Rows	2
Keying	Reverse



Electrical Characteristics

DRAM Voltage	2.5 V
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Signal Characteristics

SGRAM Voltage	2.5 V
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Body Features

Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking
Connector Profile	Standard

Contact Features

Socket Style	SO DIMM
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card

Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	.6 mm[.024 in]
Housing Color	Gray
Housing Material	High Temperature Thermoplastic

Dimensions

Stack Height	6.5 mm[.256 in]
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Row-to-Row Spacing	6.2 mm[.244 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Semi-Hard Tray Assembly
Packaging Quantity	20

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUN 2020 (209) Candidate List Declared Against: JAN 2020 (205) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

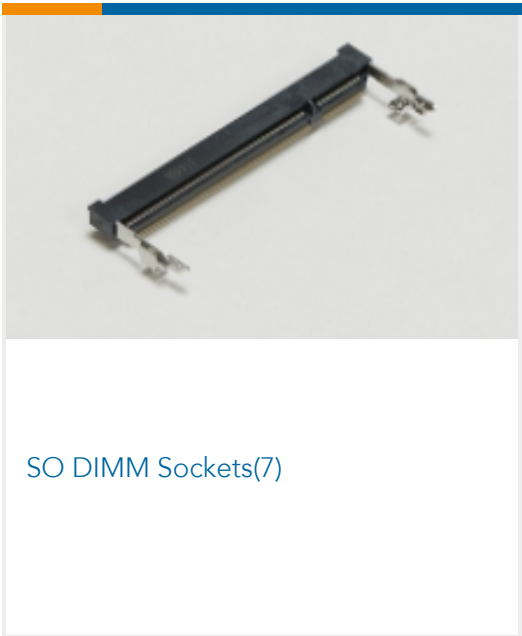
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

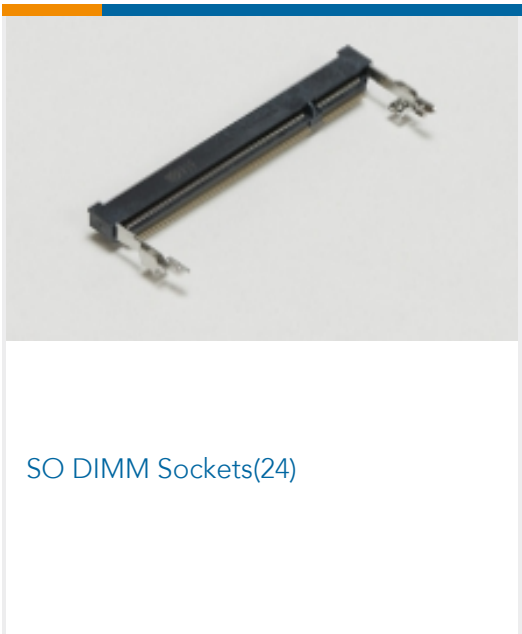
Compatible Parts



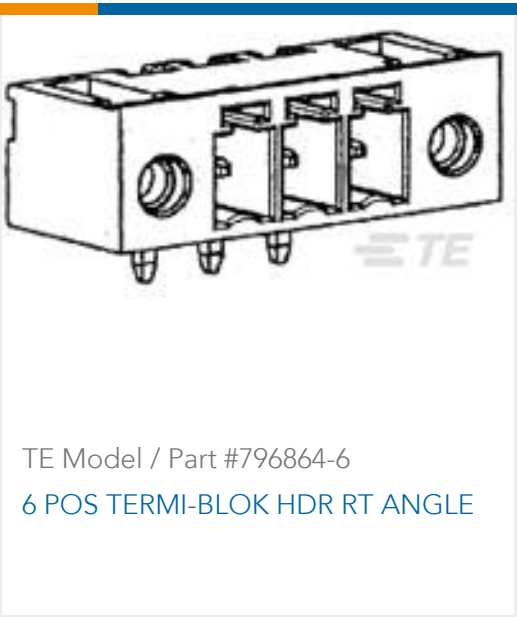
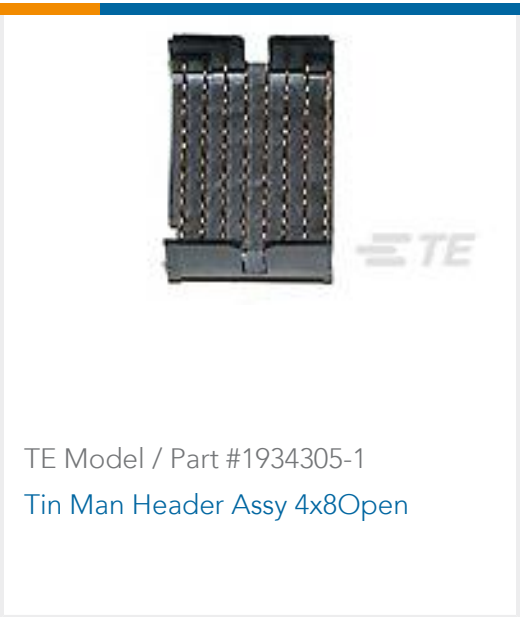
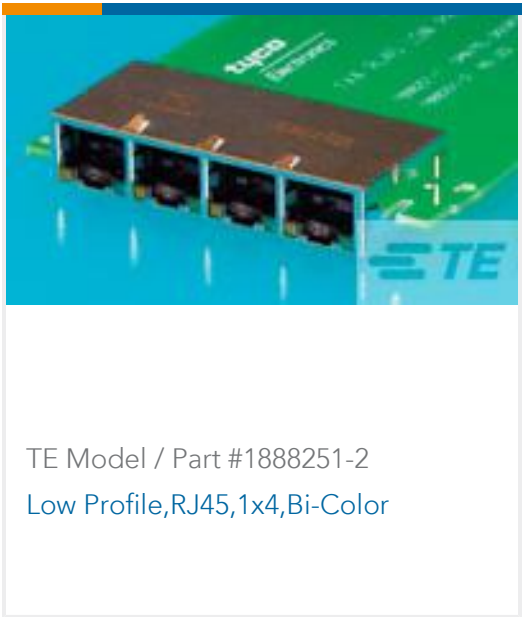
Also in the Series | [DDR SODIMM](#)



Also in the Series | [DDR2 SO DIMM](#)

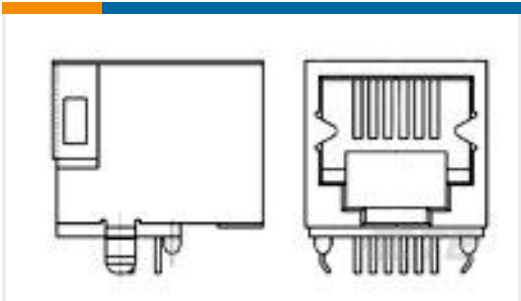


Customers Also Bought





TE Model / Part #5787617-3  
RECP ASSY, R/A, STACKED, THRU-HOLE, USB,



TE Model / Part #1734723-6  
RJ11,6P6C,SINGLE,DIP, 15u" Au, Reel

Documents

Product Drawings

SEMI-HARD TRAY DDR SODIMM 200P

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_5-1612773-1\_G1.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_5-1612773-1\_G1.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_5-1612773-1\_G1.3d\_stp.zip

English

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Product Specifications

Product Specification

English